

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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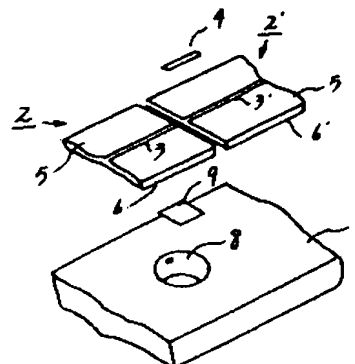
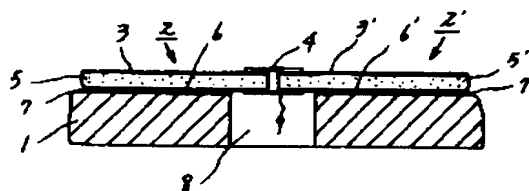
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TITLE : CONSTRUCTION OF MICROWAVE  
AND MILLIMETER WAVE INTEGRATED  
CIRCUIT



ABSTRACT : PURPOSE: To improve the matching characteristic by providing an escape hole to the lower part of a connecting part of an integrated circuit board of a metallic carrier bonded on the same plane for transmitting plural microwaves and millimeter waves so as to bond a grounding section.

CONSTITUTION: The escape hole 8 is provided to the metallic carrier 1 to which the microwave integrated circuit boards 2, 2' are connected. The microwave integrated circuit boards 2, 2' are mounted and bonded to the metallic carrier 1 by adhesives 7, 7'. A grounding conductor connecting sheet 9 is bonded from the escape hole 8 of the metallic carrier to grounding conductors 6, 6' of the connecting part of the microwave integrated circuit boards 2, 2' by bonding so as to obtain the bonding of the same level as a conductor ribbon 4 connecting transmission lines 3, 3'. Thus, plural integrated circuits are connected with good matching.

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